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Chan et al.

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(54) **FLIP CHIP**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; D14/435, 436, 437; 257/678, 257/690, 679; 361/679.31, 718, 719, 720, 361/728, 737, 752, 760, 820
See application file for complete search history.

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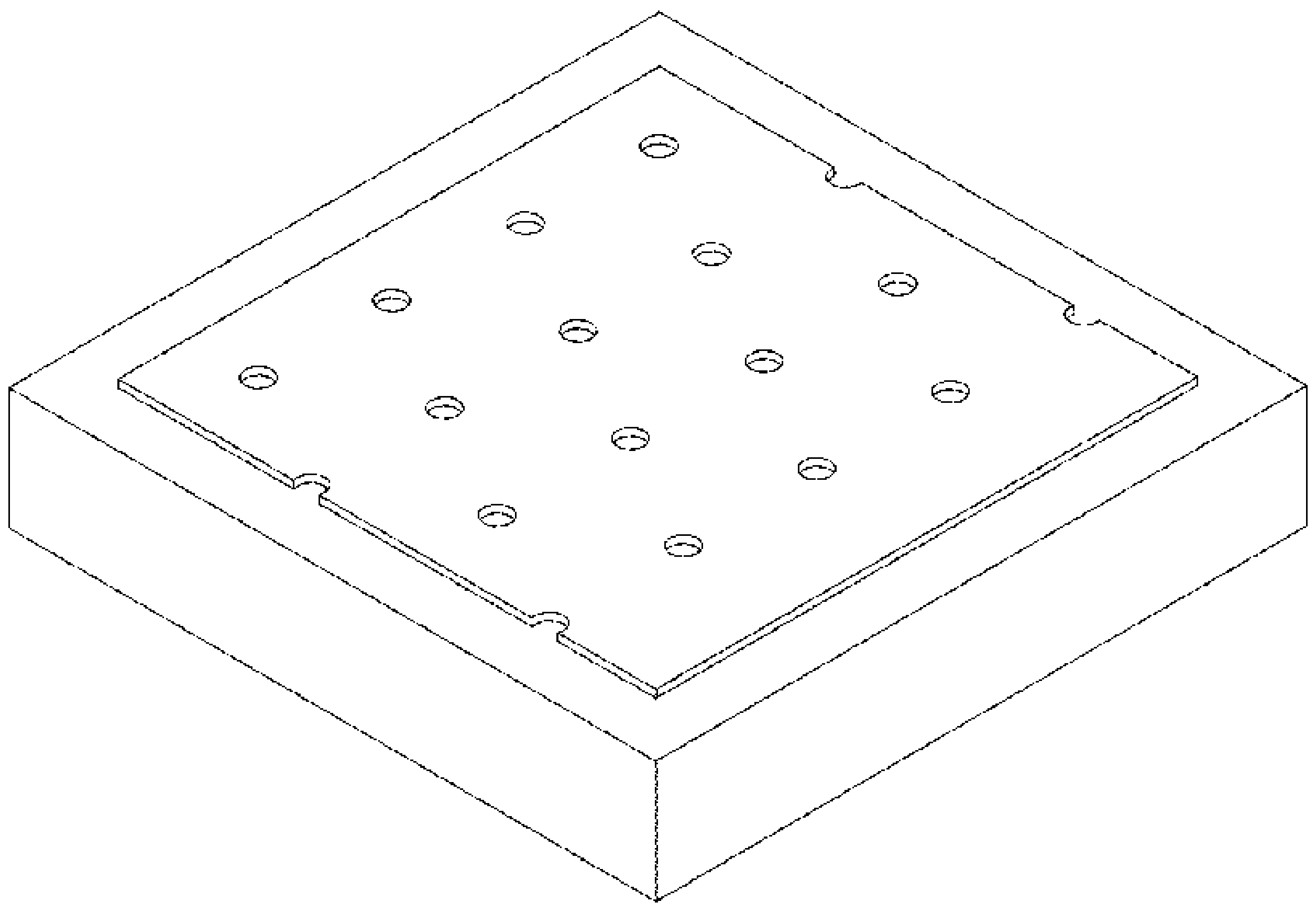
(57) **CLAIM**

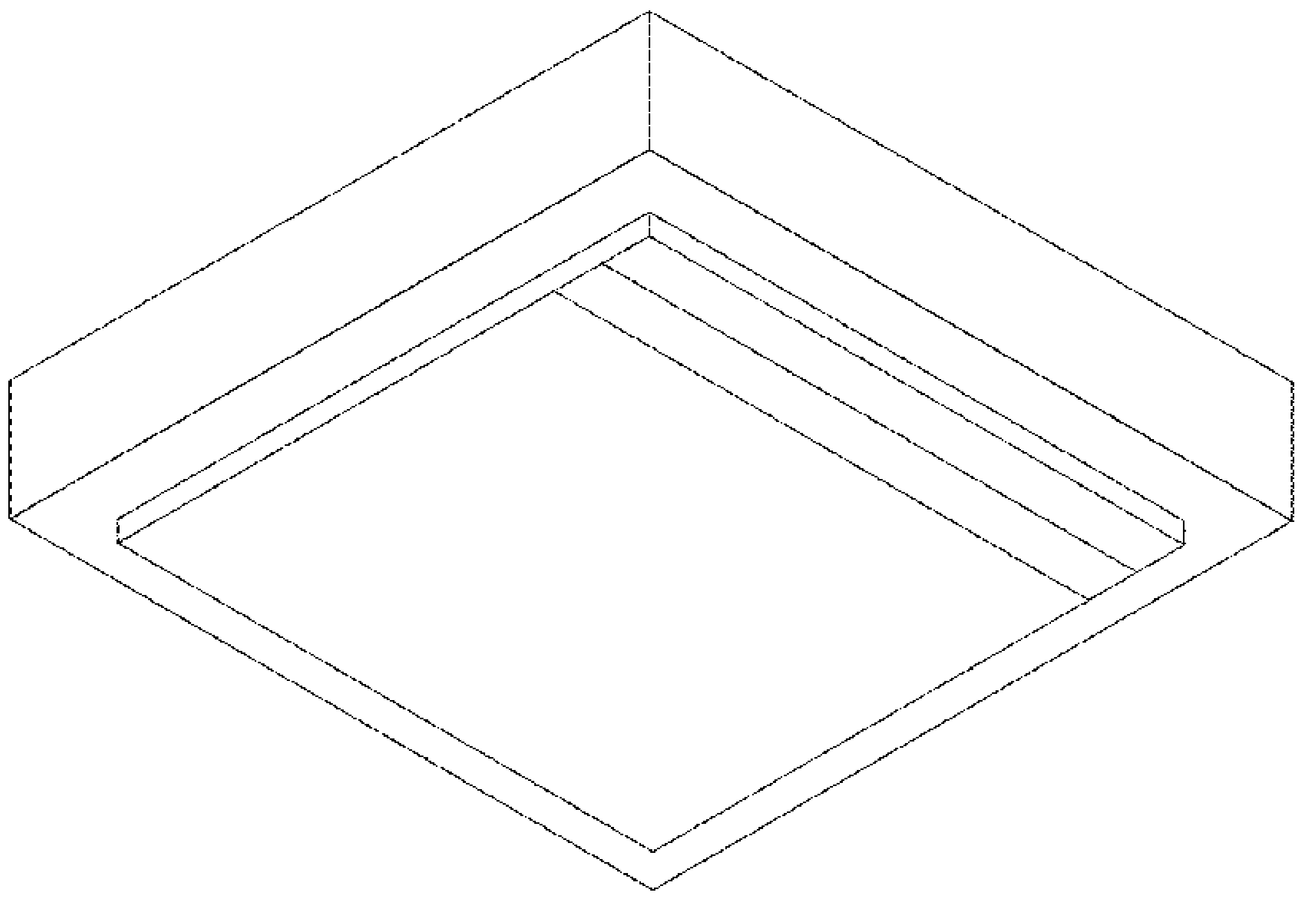
The ornamental design for a flip chip, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a flip chip showing my new design;
FIG. **2** is a front view thereof;
FIG. **3** is a back view thereof;
FIG. **4** is a left view thereof;
FIG. **5** is a right view thereof;
FIG. **6** is a top view thereof;
FIG. **7** is a bottom view thereof; and,
FIG. **8** is a bottom perspective view thereof.

1 Claim, 5 Drawing Sheets





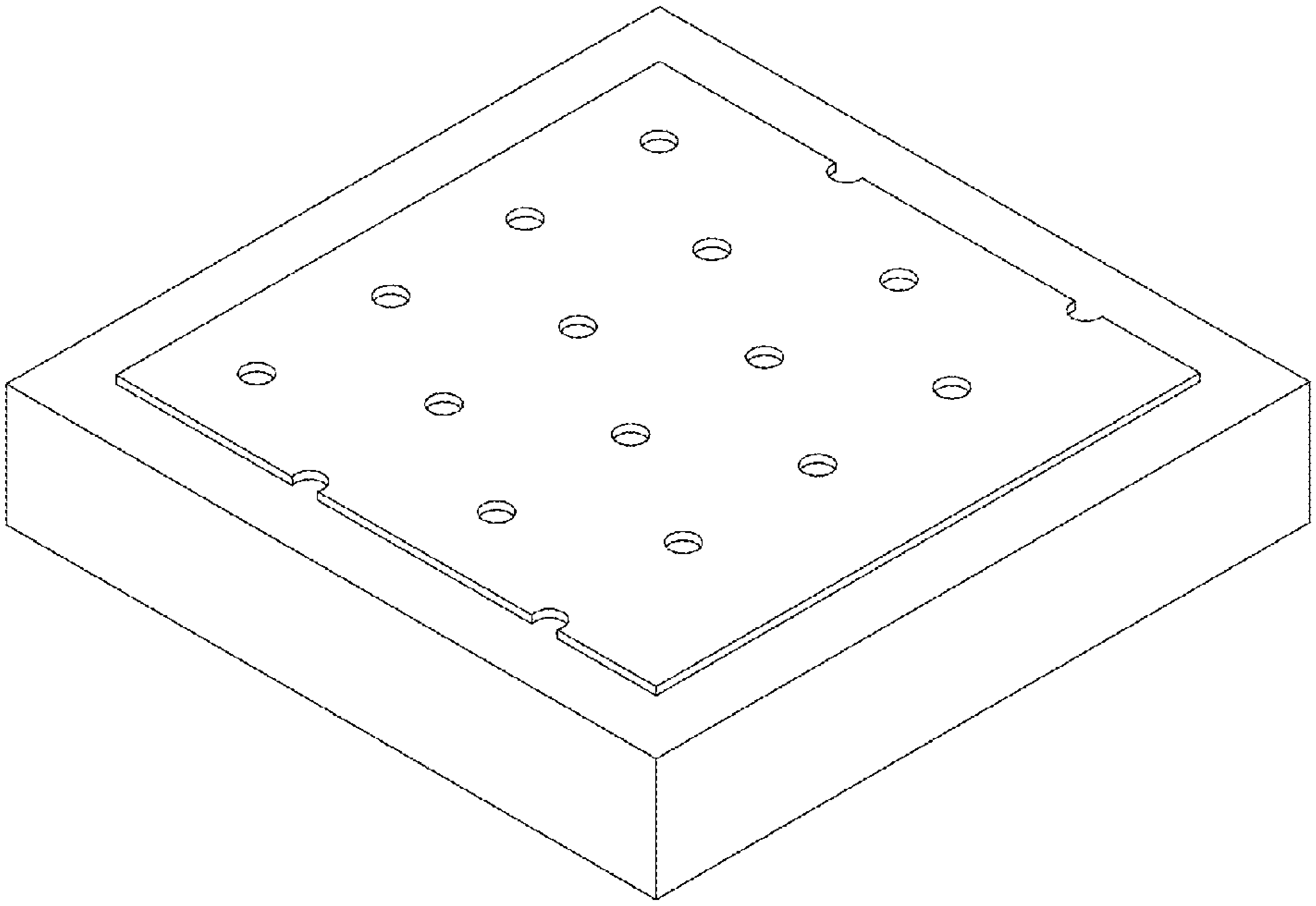


FIG.1

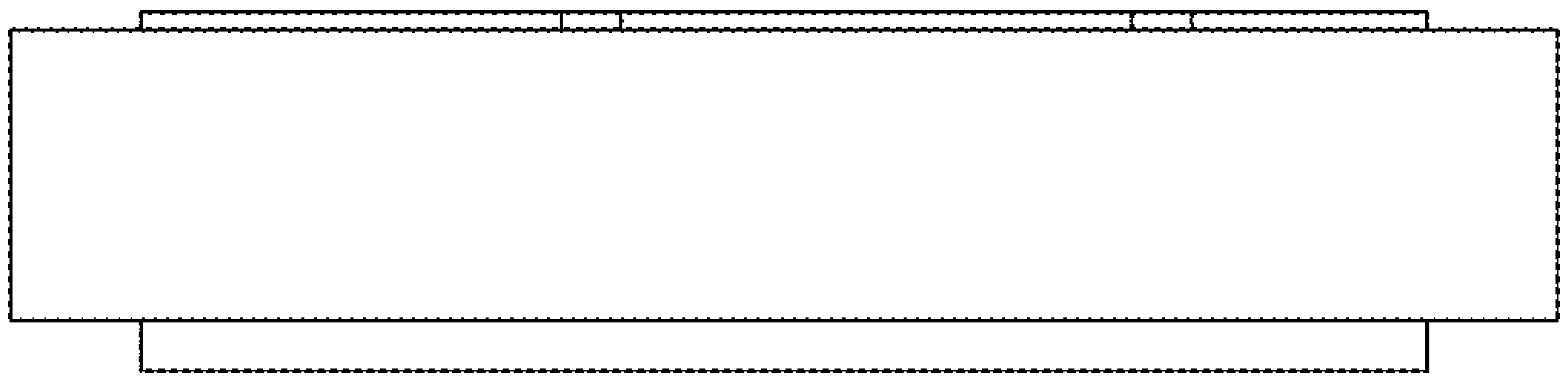


FIG.2

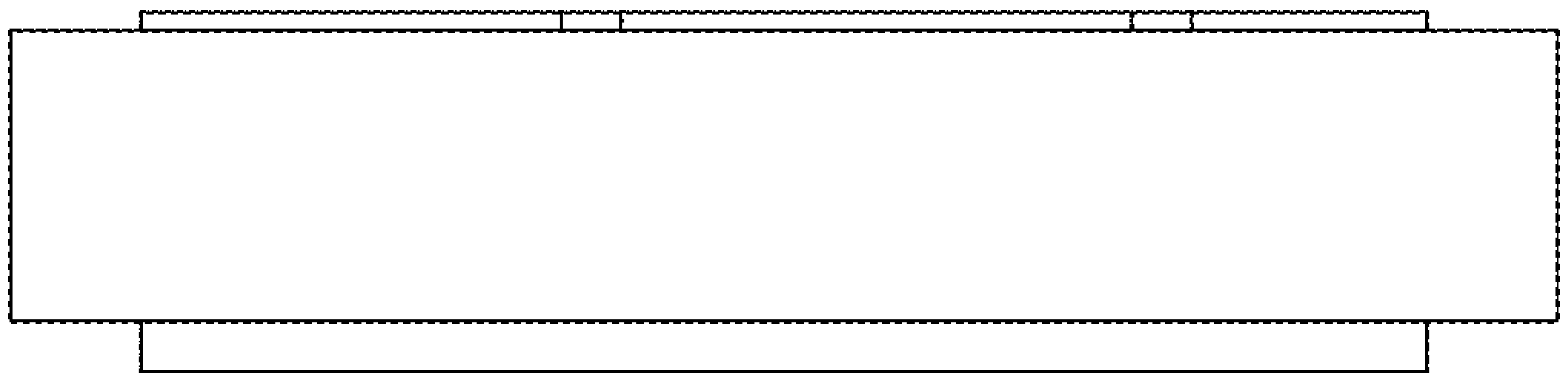


FIG.3

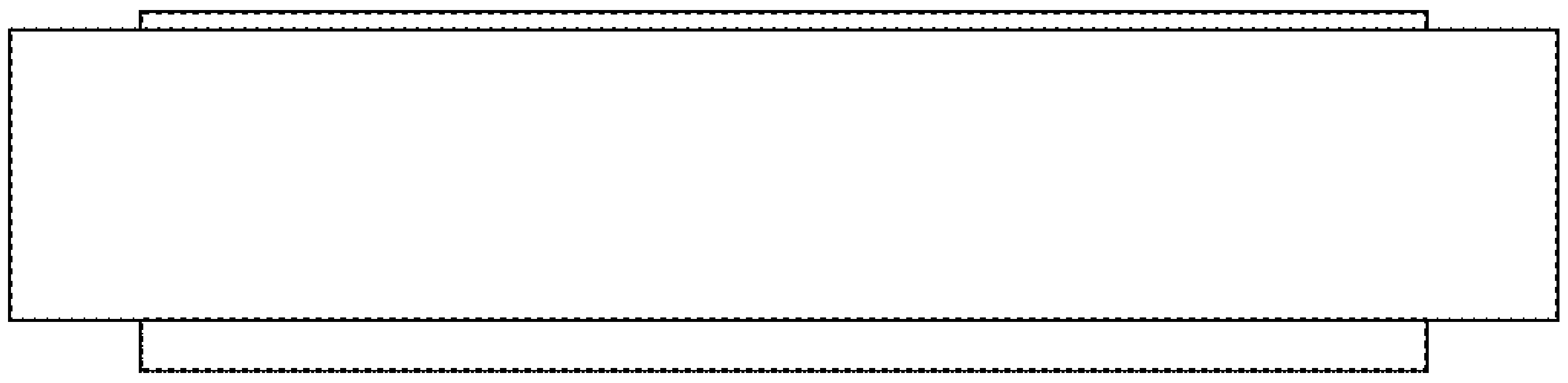


FIG.4

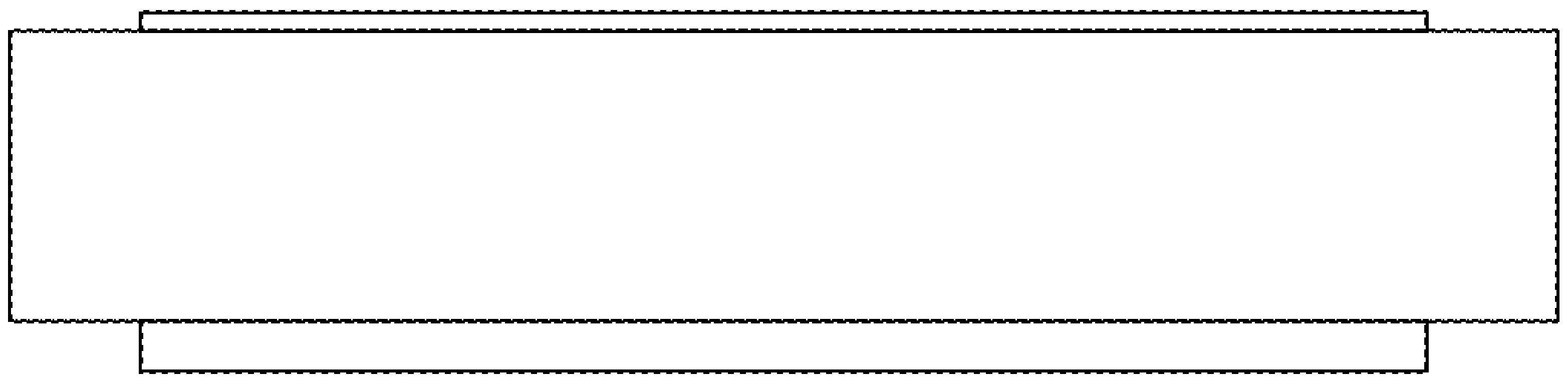


FIG.5

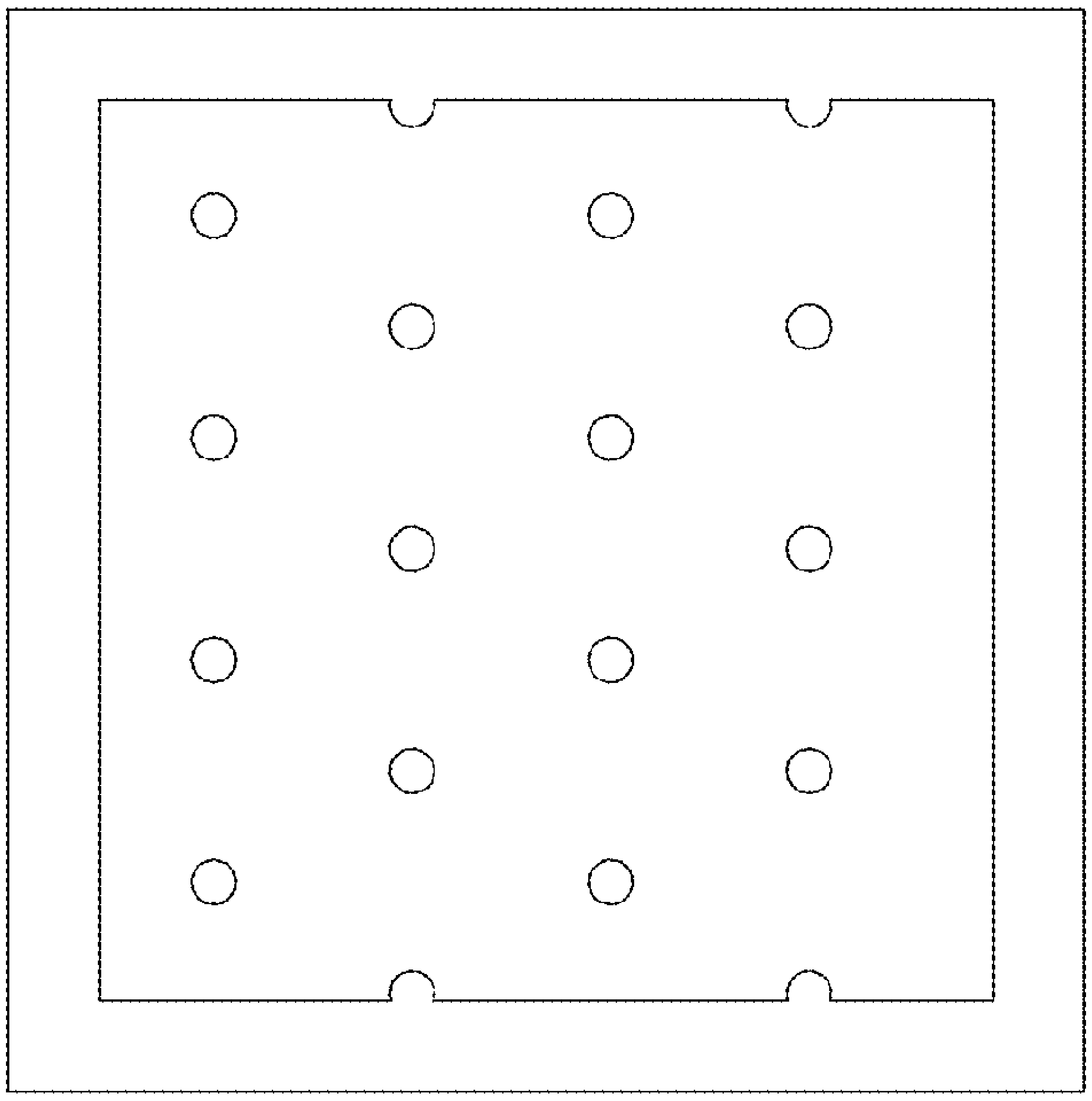


FIG.6

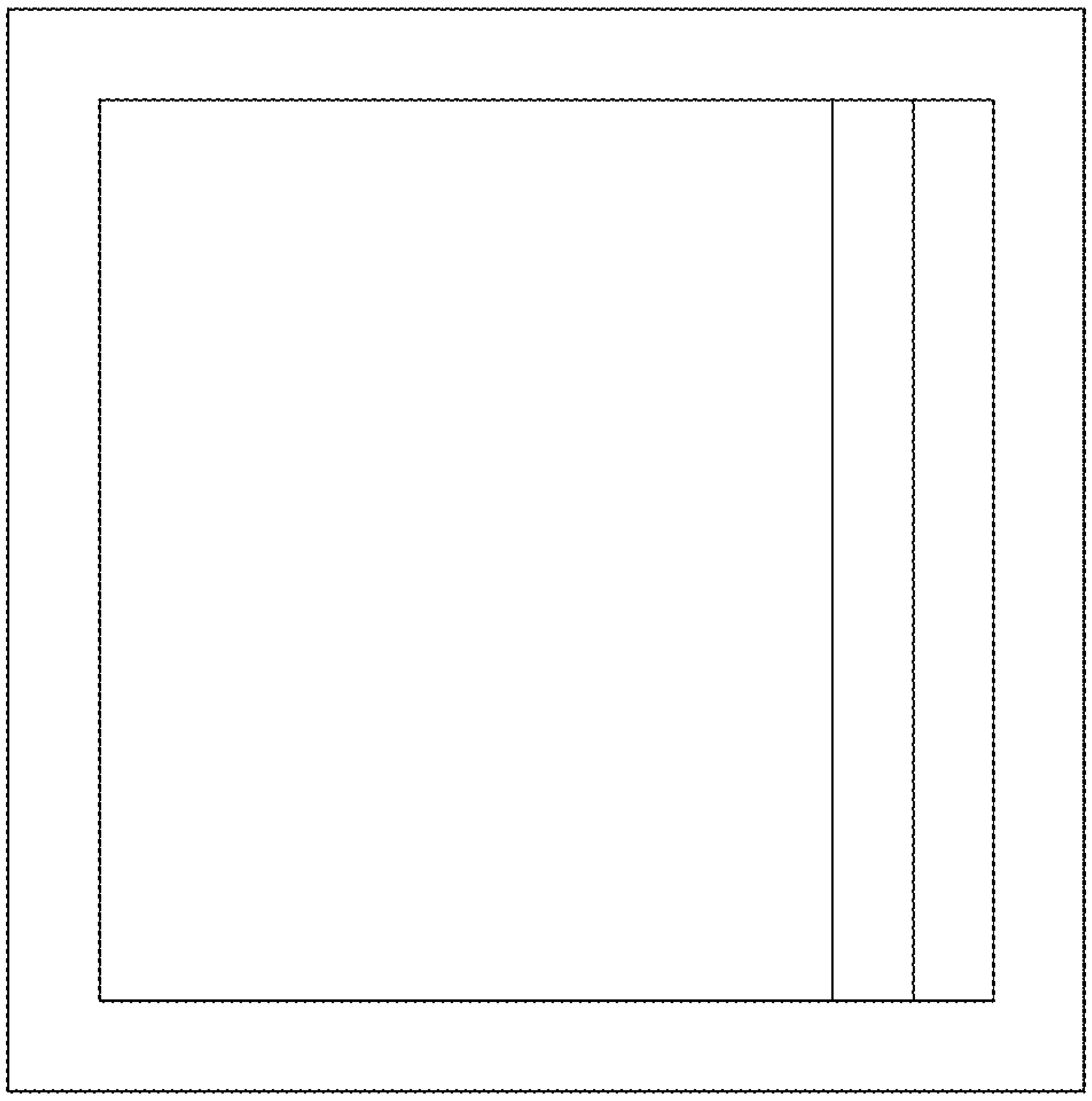


FIG.7

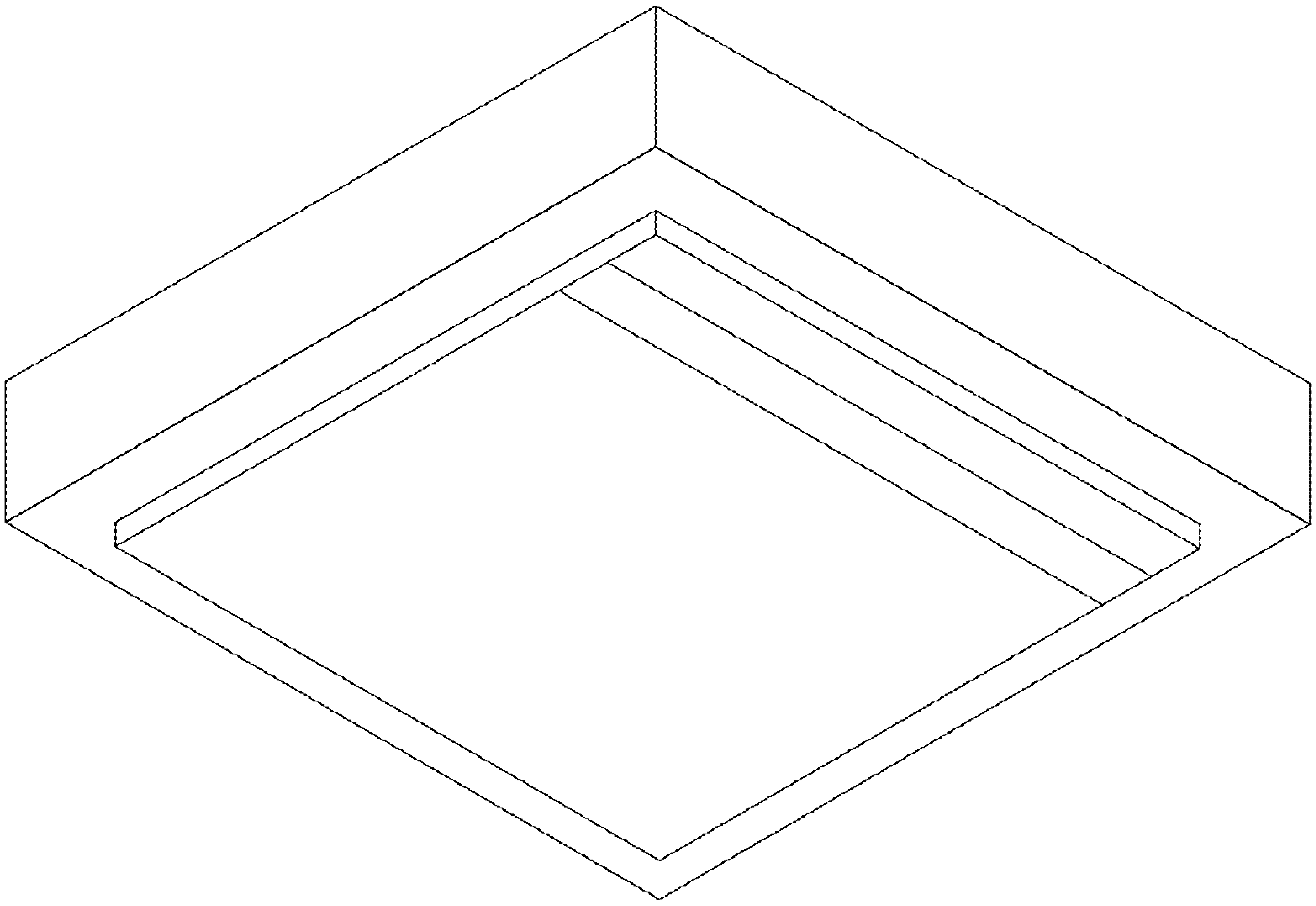


FIG.8